



General-Purpose High-Voltage Open-Drain Output Quad Comparators

1 FEATURES

- Supply Range: +3.3V to +32V
- Low Supply Current
 45μA (TYP) per channel at V_s = 5V
- Common-Mode Input Voltage Range Includes Ground
- Low Output Saturation Voltage
- Open-Drain Output for Maximum Flexibility
- SPECIFIED UP TO +125°C
- PACKAGES: SOP14, TSSOP14

2 APPLICATIONS

- Hysteresis Comparators
- Factory Automation & Control
- Industrial Equipment
- Test and Measurement
- Cordless Power Tool
- Vacuum Robot
- Wireless Infrastructure

3 DESCRIPTIONS

The LM2901 is the quad comparators version, and the outputs can be connected to other open-collector outputs to achieve wired-AND relationships. It can operate from 3.3V to 32V, and have low power consuming $45\mu A$ (TYP) per channel.

The LM2901 consist of four independent voltage comparators that are designed to operate from a single power supply over a wide range of voltages. Quiescent current is independent of the supply voltage. The device is the most cost-effective solutions for applications where low offset voltage, high supply voltage capability, low supply current, and space saving are the primary specifications in circuit design for portable consumer products.

The LM2901 is available in Green SOP14, TSSOP14 packages. It operates over an ambient temperature range of -40°C to +125°C.

Device Information (1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
LM2901	SOP14	8.65mm×3.90mm
	TSSOP14	5.00mm×4.40mm

 For all available packages, see the orderable addendum at the end of the data sheet.



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4 Revision History

Note: Page numbers for previous revisions may different from page numbers in the current version.

VERSION	Change Date	Change Item
A.0	2020/11/05	Initial version completed
A.1	2021/07/05	Correction of SOP14 orderable device in Page 5@ A.0 Version
A.2	2022/03/16	Increase the minimum junction temperature Add the schematic diagram of comparator in the pin configuration and functions diagram Change ESD Ratings
A.3	2022/07/15	1. Change Supply Range: +3.3V to +32V 2. Added CDM ESD Ratings
A.4	2022/08/08	Change KEY PARAMETER LIST OF TAPE AND REEL in Page 15@ A.3 Version
A.4.1	2024/02/23	Modify packaging naming
A.5	2024/03/27	Added MSL on Page 4@RevA.4.1 Update Package thermal impedance Update PACKAGE note



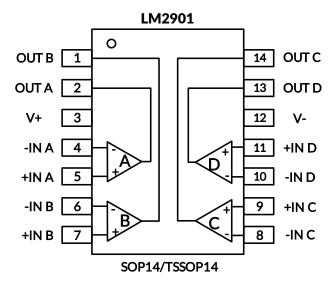
5 PACKAGE/ORDERING INFORMATION (1)

Orderable Device	Package Type	Pin	Channel	Op Temp(°C)	Device Marking ⁽²⁾	MSL ⁽³⁾	Package Qty
LM2901XP	SOP14	14	4	-40°C ~+125°C	LM2901	MSL3	Tape and Reel, 4000
LM2901XQ	TSSOP14	14	4	-40°C ~+125°C	LM2901	MSL3	Tape and Reel, 4000

- (1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.
- (2) There may be additional marking, which relates to the lot trace code information (data code and vendor code), the logo or the environmental category on the device.
- (3) MSL, The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications.



6 Pin Configuration and Functions (Top View)



Pin Description

i iii Descrip	<u></u>		
NAME	PIN	1/0(1)	DESCRIPTION
NAME	SOP14/TSSOP14	I/O ⁽¹⁾	DESCRIPTION
OUTB	1	0	Output, channel B
OUTA	2	0	Output, channel A
V+	3	Р	Positive (highest) power supply
-INA	4	I	Inverting input, channel A
+INA	5	1	Noninverting input, channel A
-INB	6	1	Inverting input, channel B
+INB	7	I	Noninverting input, channel B
-INC	8	I	Inverting input, channel C
+INC	9	1	Noninverting input, channel C
-IND	10	I	Inverting input, channel D
+IND	11	I	Noninverting input, channel D
V-	12	Р	Negative (lowest) power supply
OUTD	13	0	Output, channel D
OUTC	14	0	Output, channel C

⁽¹⁾ I=Input, O=Output, P=Power.



7 SPECIFICATIONS

7.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) (1)

			MIN	MAX	UNIT
	Supply, V _S =(V+) - (V-)			36	
Voltage	Input pin (IN+, IN-) (2)		(V-)-0.3	(V+) +0.3	V
	Signal output pin ⁽³⁾		(V-)-0.3	(V+) +0.3	
	Signal input pin (IN+, IN-) (2)	-10	10	mA	
Current	Signal output pin ⁽³⁾	-55	55	mA	
	Output short-circuits (4)	Conti	Continuous		
0	D1 th (5)	SOP14		105	9C /\A/
Αιθ	Package thermal impedance (5)	TSSOP14		90	°C/W
	Operating range, T _A	-40	125		
Temperature	Junction, T _J ⁽⁶⁾	-40	150	°C	
	Storage, T _{stg}	-65	150		

⁽¹⁾ Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

- (4) Short-circuit from output to V_{CC} can cause excessive heating and eventual destruction.
- (5) The package thermal impedance is calculated in accordance with JESD-51.
- (6) The maximum power dissipation is a function of T_{J(MAX)}, R_{θJA}, and T_A. The maximum allowable power dissipation at any ambient temperature is P_D = (T_{J(MAX)} T_A) / R_{θJA}. All numbers apply for packages soldered directly onto a PCB.

7.2 ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

			VALUE	UNIT
		Human-Body Model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins (1)	±2000	
V _(ESD)	Electrostatic discharge	Charged-Device Model (CDM), per ANSI/ESDA/JEDEC JS-002 (2)	±1500	V
		Machine Model (MM)	±200	

⁽¹⁾ JEDEC document JEP155 states that 500 V HBM allows safe manufacturing with a standard ESD control process.

⁽²⁾ JEDEC document JEP157 states that 250 V CDM allows safe manufacturing with a standard ESD control process.



ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

7.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT	
Supply valtage V = (VI) (V)	Single-supply	3.3		32	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
Supply voltage, V _S = (V+) - (V-)	Dual-supply	±1.65		±16	٧	

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⁽²⁾ Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.3V beyond the supply rails should be current-limited to 10mA or less.

⁽³⁾ Output terminals are diode-clamped to the power-supply rails. Output signals that can swing more than 0.3V beyond the supply rails should be current-limited to ±55mA or less.



7.4 ELECTRICAL CHARACTERISTICS

(At $T_A = +25$ °C, $V_{CM}=(V_S/2)$, $V_S=5V$, unless otherwise noted.) (1)

	PARAMETER Operating Voltage Pange		CONDITIONS		LINUTC		
			CONDITIONS	MIN ⁽²⁾	TYP ⁽³⁾	MAX ⁽²⁾	UNITS
Vs	Operating Voltage Range			3.3		32	V
			V _S =5V, no load		180	360	
Ιq	Quiescent Current		V _S =32V, no load, T _A =-40°C to +125°C		220		μΑ
			V _S =5V to 32V	-4.5	±0.8	4.5	
Vos	Input offset voltage		V _S =5V to 32V T _A =-40°C to +125°C	-5		5	mV
ID	L L D' C L (4)/5)		T _A =25°C		10	50	pА
IB	Input Bias Current (4)(5)		T _A =-40°C to +125°C			100	nA
	Input Offset Current (4)		T _A =25°C		10	50	pА
los			T _A =-40°C to +125°C			100	nA
			V _S =3.3V to 32V	(V-)		(V+)-1.5	
V_{CM}	Common-Mode Voltage Range		V _S =3.3V to 32V T _A =-40°C to +125°C	(V-)		(V+)-2.0	V
Avd	Large signal differential voltage amplification		V _S =15V, V _O =1.4V to 11.4V R _L ≥15k to (V+)	50	200		V/mV
V_{OL}	Low-Level output voltage		I _{sink} ≤4mA, V _{ID} =-1V		200	300	mV
loL	Output Current(sinking)		V _O =1.5V; V _{ID} =-1V; V _S =5V	9	23		mA
			(V+) =Vo=5V; V _{ID} =1V		80	400	nA
I _{OH-LKG}	High-Level Output Leakage	Current	(V+) =Vo=32V; V _{ID} =1V		100	500	nA
Switchin	ng Characteristics					•	
		V _S =5V	RPU=5.1KΩ, Overdrive =10mV		2.0		
T_PHL	Propagation Delay H To L	VS-3V	RPU= $5.1K\Omega$, Overdrive = $100mV$		0.4		
I PHL	(6)	V _S =32V	RPU= $5.1K\Omega$, Overdrive = $10mV$		2.2		
		V _S -32V	RPU= $5.1K\Omega$, Overdrive = $100mV$		0.4		
		\	RPU=5.1KΩ, Overdrive =10mV		2.5		μs
-	Propagation Delay L To H	V _S =5V Delay I. To H	RPU=5.1KΩ, Overdrive =100mV		0.8		
T_PLH	(6)) (00) (RPU= $5.1K\Omega$, Overdrive = $10mV$		2.2		
		V _S =32V	RPU= $5.1K\Omega$, Overdrive = $100mV$		0.7		

⁽¹⁾ Electrical table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device.

⁽²⁾ Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.

⁽³⁾ Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.

⁽⁴⁾ This parameter is ensured by design and/or characterization and is not tested in production.

⁽⁵⁾ Positive current corresponds to current flowing into the device.

⁽⁶⁾ High-to-low and low-to-high refers to the transition at the input.



7.5 TYPICAL CHARACTERISTICS

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

At $T_A = +25$ °C, $V_S = 5V$, $R_{PULLUP} = 5.1k$, $V_{CM} = V_S/2$, $C_L = 15$ pF, unless otherwise noted.

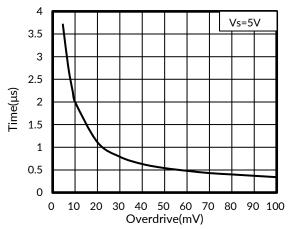


Figure 1. Response Time vs Input Overdrives
Negative Transition

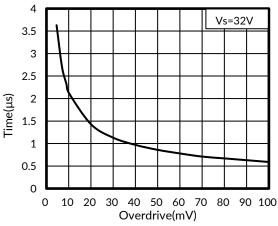


Figure 3. Response Time vs Input Overdrives
Negative Transition

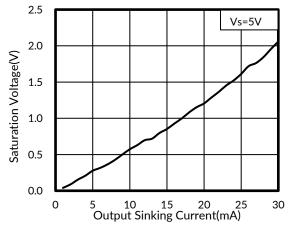


Figure 5. Saturation Voltage vs Output Sink Current

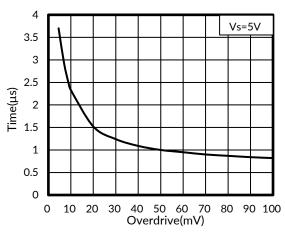


Figure 2. Response Time vs Input Overdrives
Positive Transition

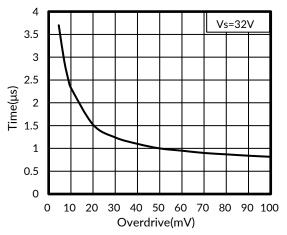


Figure 4. Response Time vs Input Overdrives
Positive Transition

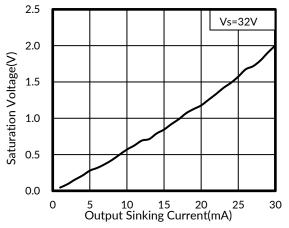


Figure 6. Saturation Voltage vs Output Sink Current

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8 Detailed Description

8.1 Overview

The LM2901 family of comparators can operate up to 32V on the supply pin. This standard device has proven ubiquity and versatility across a wide range of applications. This is due to its low power and high speed. The open-drain output allows the user to configure the output's logic low voltage (V_{OL}) and can be utilized to enable the comparator to be used in AND functionality.

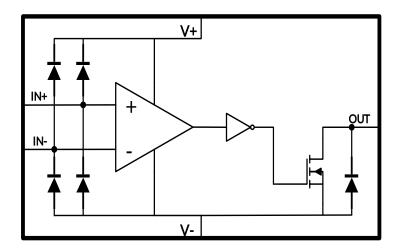


Figure 7. Functional Block Diagram



9 Application and Implementation

Information in the following applications sections is not part of the RUNIC component specification, and RUNIC does not warrant its accuracy or completeness. RUNIC's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

LM2901 is typically used to compare a single signal to a reference or two signals against each other. Many users take advantage of the open drain output (logic high with pull-up) to drive the comparison logic output to a logic voltage level to an MCU or logic device. The wide supply range and high voltage capability makes this comparator optimal for level shifting to a higher or lower voltage.

9.2 Typical Application

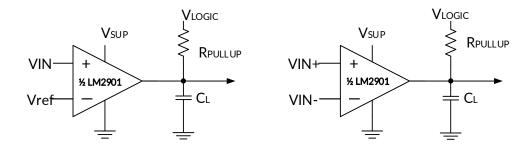


Figure 8. Single-Ended and Differential Comparator Configurations

9.3 Detailed Design Procedure

When using the device in a general comparator application, determine the following:

- Input Voltage Range
- Minimum Overdrive Voltage
- Output and Drive Current
- Response Time

9.4 Input Voltage Range

When choosing the input voltage range, the input common mode voltage range (V_{ICR}) must be taken in to account. If temperature operation is below 25°C the V_{ICR} can range from 0 V to V_{CC} – 2.0 V. This limits the input voltage range to as high as V_{CC} – 2.0 V and as low as 0 V. Operation outside of this range can yield incorrect comparisons.

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10 Layout

10.1 Layout Guidelines

For accurate comparator applications without hysteresis, it is important maintain a stable power supply with minimized noise and glitches. To achieve this, it is best to add a bypass capacitor between the supply voltage and ground. This should be implemented on the positive power supply and negative supply (if available). If a negative supply is not being used, do not put a capacitor between the IC's GND pin and system ground. Minimize coupling between outputs and inverting inputs to prevent output oscillations. Do not run output and inverting input traces in parallel unless there is a $V_{\rm CC}$ or GND trace between output and inverting input traces to reduce coupling. When series resistance is added to inputs, place resistor close to the device.

10.2 Layout Example

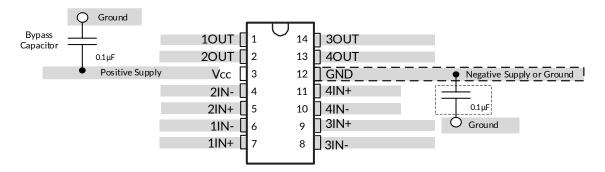
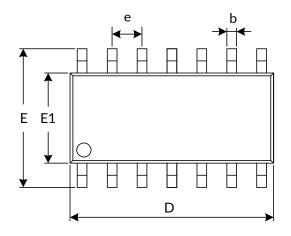
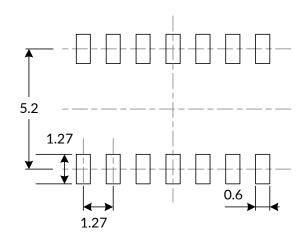


Figure 9. LM2901 Layout Example

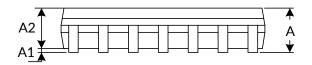


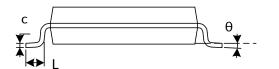
11 PACKAGE OUTLINE DIMENSIONS SOP14 (3)





RECOMMENDED LAND PATTERN (Unit: mm)



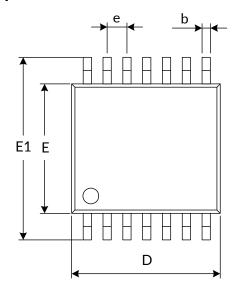


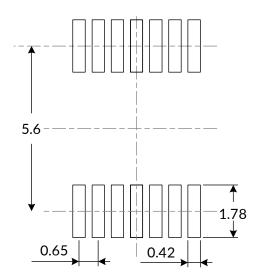
Combal	Dimensions I	n Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
A (1)	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.310	0.510	0.012	0.020	
С	0.100	0.250	0.004	0.010	
D (1)	8.450	8.850	0.333	0.348	
е	1.270(BSC) (2)	0.050(BSC) (2)		
E	5.800	6.200	0.228	0.244	
E1 ⁽¹⁾	3.800	4.000	0.150	0.157	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	

- 1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
- 2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
- 3. This drawing is subject to change without notice.



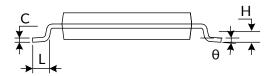
TSSOP14 (3)





RECOMMENDED LAND PATTERN (Unit: mm)





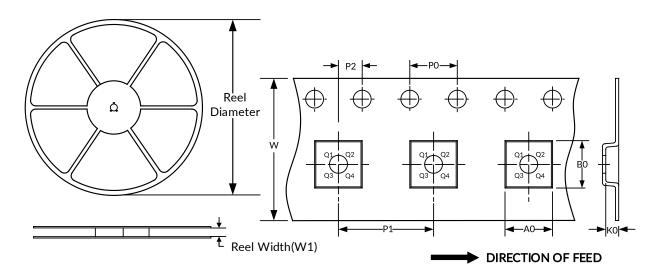
Complete	Dimensions I	n Millimeters	Dimension	s In Inches	
Symbol	Min	Max	Min	Max	
A (1)		1.200		0.047	
A1	0.050	0.150	0.002	0.006	
A2	0.800	1.050	0.031	0.041	
b	0.190	0.300	0.007	0.012	
С	0.090	0.200	0.004	0.008	
D (1)	4.860	5.100	0.191	0.201	
E (1)	4.300	4.500	0.169	0.177	
E1	6.250	6.550	0.246	0.258	
е	0.650(BSC) (2)	0.026(BSC) (2)	
L	0.500	0.700	0.020	0.028	
Н	0.25(TYP)		0.01(TYP)		
θ	1°	7°	1°	7°	

- Plastic or metal protrusions of 0.15mm maximum per side are not included.
 BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
 This drawing is subject to change without notice.



12 TAPE AND REEL INFORMATION REEL DIMENSIONS

TAPE DIMENSION



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SOP14	13"	16.4	6.60	9.30	2.10	4.0	8.0	2.0	16.0	Q1
TSSOP14	13"	12.4	6.95	5.60	1.20	4.0	8.0	2.0	12.0	Q1

- 1. All dimensions are nominal.
- 2. Plastic or metal protrusions of 0.15mm maximum per side are not included.



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